

**AMENDMENTS TO THE CLAIMS:**

1. (Original) A polishing method for polishing a workpiece, comprising:  
polishing a surface of a workpiece by pressing said surface of said workpiece against a polishing surface of a polishing table under a predetermined force;  
polishing an outer peripheral portion of said workpiece before or after said polishing of said surface of said workpiece by pressing said outer peripheral portion of said workpiece against an outer periphery polishing surface of a rotating outer periphery polishing unit; and  
directing a polishing liquid to said rotating outer periphery polishing unit about a rotational center thereof such that said polishing liquid is supplied to said outer periphery polishing surface via centrifugal force caused by the rotation of said outer periphery polishing unit.
2. (Original) The polishing method according to claim 1, wherein pressing said surface of said workpiece against said polishing surface comprises holding said workpiece with a top ring and pressing said workpiece against said polishing surface via said top ring.
3. (Original) The polishing method according to claim 2, wherein polishing said outer peripheral portion said workpiece comprises holding said workpiece with said top ring and pressing said outer peripheral portion of said workpiece against said outer periphery polishing surface of said rotating outer periphery polishing unit.
4. (Original) The polishing method according to claim 1, wherein said workpiece comprises a substrate on which copper interconnects are formed.
5. (Original) The polishing method according to claim 4, wherein said polishing liquid has a polishing rate for copper which is at least ten times greater than that for an oxide film or a low-K material.

*Claims 6-16 (Withdrawn)*

17. (Original) A polishing method for polishing a workpiece having a film formed thereon, said polishing method comprising:

polishing a surface of a workpiece by pressing said surface of said workpiece against a polishing surface of a polishing table under a predetermined force;

polishing an outer peripheral portion of said workpiece before or after said polishing of said surface of said workpiece by pressing said outer peripheral portion of said workpiece against an outer periphery polishing surface of a rotating outer periphery polishing unit; and

directing a polishing liquid to said rotating outer periphery polishing unit about a rotational center thereof such that said polishing liquid is supplied to said outer periphery polishing surface via centrifugal force caused by the rotation of said outer periphery polishing unit.

*Claims 18-19 (Withdrawn)*

20. (Original) A polishing method for polishing a workpiece, comprising:

polishing a surface of a workpiece by pressing said surface of said workpiece against a polishing surface;

polishing an outer peripheral portion of said workpiece before or after said polishing of said surface of said workpiece by pressing said outer peripheral portion of said workpiece against an outer periphery polishing surface of a rotating outer periphery polishing unit; and

directing a polishing liquid to said rotating outer periphery polishing unit about a rotational center thereof.

21. (New) A polishing method for polishing a workpiece, comprising:

holding a workpiece with a top ring and pressing a surface of said workpiece against a polishing surface of a polishing table so as to polish said surface of said workpiece;

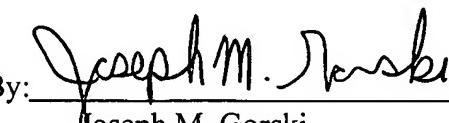
polishing an outer peripheral portion of said workpiece before or after the polishing of said surface of said workpiece by pressing said outer peripheral portion of said workpiece against an outer periphery polishing surface provided so as to substantially surround said outer peripheral portion of said workpiece.

22. (New) The polishing method according to claim 21, further comprising:  
holding said workpiece by said top ring while said outer peripheral portion of said workpiece  
is polished.

Respectfully submitted,

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